

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	ISZ0501NLS	**Issued**	4. November 2019
MA#	MA005405308		
Package	PG-TSDSON-8-25	**Weight***	34.43 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.226	0.66	0.66	6557	6557
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		106	
	non noble metal	zinc	7440-66-6	0.015	0.04		422	
	non noble metal	iron	7439-89-6	0.291	0.84		8443	
	non noble metal	copper	7440-50-8	11.804	34.28	35.17	342831	351802
wire	non noble metal	copper	7440-50-8	0.014	0.04	0.04	404	404
encapsulation	organic material	carbon black	1333-86-4	0.036	0.11		1059	
	plastics	epoxy resin	-	1.879	5.46		54563	
	inorganic material	silicondioxide	60676-86-0	16.325	47.42	52.99	474117	529739
leadfinish	non noble metal	tin	7440-31-5	0.395	1.15	1.15	11480	11480
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	590	590
solder	non noble metal	tin	7440-31-5	0.008	0.02		225	
	noble metal	silver	7440-22-4	0.010	0.03		281	
	non noble metal	lead	7439-92-1	0.369	1.07	1.12	10731	11237
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001	0.00		26	
	non noble metal	zinc	7440-66-6	0.004	0.01		106	
	non noble metal	iron	7439-89-6	0.073	0.21		2117	
	non noble metal	copper	7440-50-8	2.959	8.59	8.81	85942	88191
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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